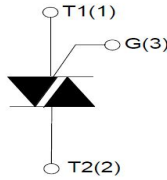
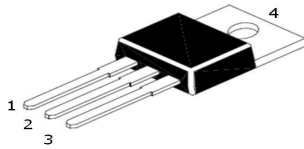


## 16A TRIACS



**BTA16-600/800/1200**  
**TO-220 (Ins)**  
**Plastic Package**

**BTB16-600/800/1200**  
**TO-220 (Non-Ins)**  
**Plastic Package**

BTA16 series triacs, with high ability to withstand the shock loading of large current, provide high dv/dt rate with strong resistance to electromagnetic interference. With high commutation performances, 3 quadrant products especially recommended for use on inductive load.

### ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Storage junction temperature range	$T_{stg}$	-40 to 150	°C
Operating junction temperature range	$T_j$	-40 to 125	°C
Repetitive peak off-state voltage ( $T_j=25^\circ\text{C}$ )	$V_{DRM}$	600/800/1200	V
Repetitive peak reverse voltage ( $T_j=25^\circ\text{C}$ )	$V_{RRM}$	600/800/1200	V
Non repetitive surge peak Off-state voltage	$V_{DSM}$	$V_{DRM} + 100$	V
Non repetitive peak reverse voltage	$V_{RSM}$	$V_{RRM} + 100$	V
RMS on-state current	TO-220 (Ins) ( $T_c=86^\circ\text{C}$ )	16	A
	TO-220 (Non-Ins) ( $T_c=107^\circ\text{C}$ )		
Non repetitive surge peak on-state current (full cycle, $F=50\text{Hz}$ )	$I_{TSM}$	160	A
$I^2t$ value for fusing ( $t_p=10\text{ms}$ )	$I^2t$	128	$\text{A}^2\text{s}$
Critical rate of rise of on-state current ( $I_G = 2 \times I_{GT}$ )	$di/dt$	50	$\text{A}/\mu\text{s}$
Peak gate current	$I_{GM}$	4	A
Average gate power dissipation	$P_{G(AV)}$	1	W
Peak gate power	$P_{GM}$	5	W

**ELECTRICAL CHARACTERISTICS** ( $T_j=25^\circ\text{C}$  unless otherwise specified)

**3 Quadrants ( $V_{\text{DRM}}/V_{\text{RRM}} : 600/800\text{V}$ )**

PARAMETER	TEST CONDITIONS	SYMBOL	QUADRANT	VALUES				UNITS
				BW	CW	SW	TW	
Gate Trigger Current	$V_D = 12\text{V}$ $R_L = 33\Omega$	$I_{\text{GT}}$	I - II - III	<50	<35	<10	<5	mA
Gate Trigger Voltage		$V_{\text{GT}}$	I - II - III	<1.3				V
Off-State Gate Voltage	$V_D = V_{\text{DRM}}$ $T_j = 125^\circ\text{C}$ $R_L = 3.3\text{K}\Omega$	$V_{\text{GD}}$	I - II - III	>0.2				V
Latching Current	$I_G = 1.2I_{\text{GT}}$	$I_L$	I - III	<70	<50	<30	<15	mA
			II	<80	<60	<40	<20	
Holding Current	$I_T = 100\text{mA}$	$I_H$		<60	<40	<25	<15	mA
Critical Rate of Rise of Off-State Voltage	$V_D = 2/3V_{\text{DRM}}$ Gate Open $T_j = 125^\circ\text{C}$	dV/dt		>1000	>500	>200	>100	V/ $\mu\text{s}$

**4 Quadrant ( $V_{\text{DRM}}/V_{\text{RRM}} : 600/800\text{V}$ )**

PARAMETER	TEST CONDITIONS	SYMBOL	QUADRANT	VALUES		UNITS
				B	C	
Gate Trigger Current	$V_D = 12\text{V}$ $R_L = 33\Omega$	$I_{\text{GT}}$	I - II - III	<50	<25	mA
			IV	<70	<50	
Gate Trigger Voltage	$V_D = 12\text{V}$ $R_L = 33\Omega$	$V_{\text{GT}}$	ALL	<1.5		V
Off-State Gate Voltage	$V_D = V_{\text{DRM}}$ $T_j = 125^\circ\text{C}$ $R_L = 3.3\text{K}\Omega$	$V_{\text{GD}}$	ALL	>0.2		V
Latching Current	$I_G = 1.2I_{\text{GT}}$	$I_L$	I - III - IV	<70	<50	mA
			II	<100	<80	
Holding Current	$I_T = 100\text{mA}$	$I_H$		<60	<40	mA
Critical Rate of Rise of Off-State Voltage	$V_D = 2/3V_{\text{DRM}}$ Gate Open $T_j = 125^\circ\text{C}$	dV/dt		>500	>200	V/ $\mu\text{s}$

### 3 Quadrants ( $V_{DRM}/V_{RRM}$ : 1200V)

PARAMETER	TEST CONDITIONS	SYMBOL	QUADRANT	VALUES	UNITS
Gate Trigger Current	$V_D = 12V$ $R_L = 33\Omega$	$I_{GT}$	I - II - III	<50	mA
Gate Trigger Voltage		$V_{GT}$	I - II - III	<1.5	V
Off-State Gate Voltage	$V_D = V_{DRM}$ $T_j = 125^\circ C$ $R_L = 3.3K\Omega$	$V_{GD}$	I - II - III	>0.2	V
Latching Current	$I_G = 1.2I_{GT}$	$I_L$	I - III	<70	mA
			II	<90	
Holding Current	$I_T = 100mA$	$I_H$		<60	mA
Critical Rate of Rise of Off-State Voltage	$V_D = 2/3V_{DRM}$ Gate Open $T_j = 125^\circ C$	dV/dt		>1500	V/ $\mu s$

### STATIC CHARACTERISTICS

PARAMETER	TEST CONDITIONS	SYMBOL	VALUE (MAX)			UNITS
			-600V	-800V	-1200V	
On-State Voltage	$I_{TM} = 22.5A$ $t_p = 380\mu s$	$T_j = 25^\circ C$ $V_{TM}$	1.5			V
Off-State Leakage Current	$V_D = V_{DRM}$ , $V_R = V_{RRM}$	$T_j = 25^\circ C$ $I_{DRM}$	5	5	10	$\mu A$
		$T_j = 125^\circ C$ $I_{RRM}$	2	2	1	mA

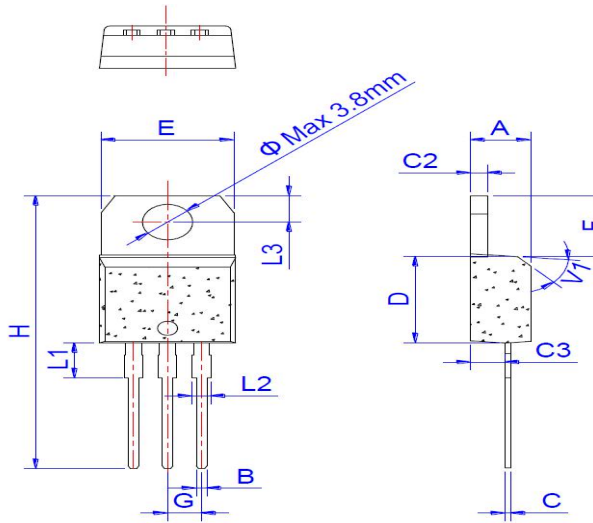
### THERMAL RESISTANCES

PARAMETER	SYMBOL	VALUE (MAX)	UNITS
Maximum Thermal Resistance	$R_{th(j-c)}$	2.1	$^\circ C/W$
		1.2	

### ORDERING INFORMATION

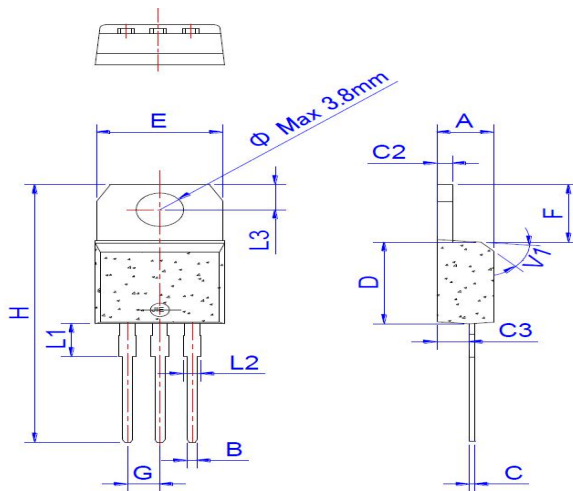
<b>BTA12-XY</b> <b>BTB12-XY</b>	
<b>X</b> = 600: $V_{DRM}/V_{RRM} \geq 600$ = 800: $V_{DRM}/V_{RRM} \geq 800$ = 1200: $V_{DRM}/V_{RRM} \geq 1200$	<b>Y</b> = BW: $I_{GT1-3} \leq 50mA$ = CW: $I_{GT1-3} \leq 35mA$ = SW: $I_{GT1-3} \leq 10mA$ = TW: $I_{GT1-3} \leq 5mA$ = B: $I_{GT1-3} \leq 50mA$ $I_{GT4} \leq 70mA$ = C: $I_{GT1-3} \leq 25mA$ $I_{GT4} \leq 50mA$

### TO-220 (Ins) PACKAGE OUTLINE AND DIMENSIONS



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	0.61		0.88	0.024		0.035
C	0.46		0.70	0.018		0.028
C2	1.21		1.32	0.048		0.052
C3	2.40		2.72	0.094		0.107
D	8.60		9.70	0.339		0.382
E	9.80		10.4	0.386		0.409
F	6.55		6.95	0.258		0.274
G		2.54			0.1	
H	28.0		29.8	1.102		1.173
L1		3.75			0.148	
L2	1.14		1.70	0.045		0.067
L3	2.65		2.95	0.104		0.116
V1		45°			45°	

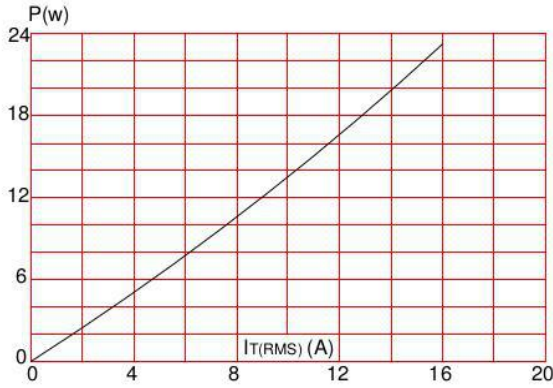
### TO-220 (Non-Ins) PACKAGE OUTLINE AND DIMENSIONS



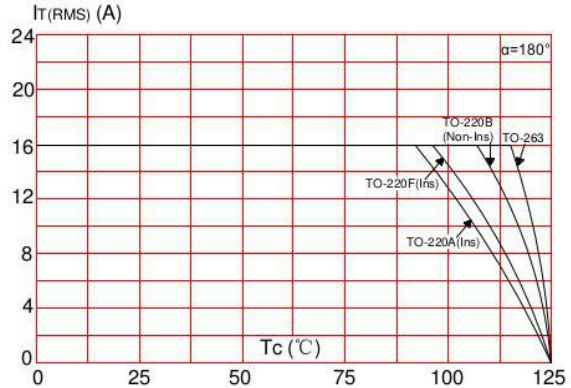
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	0.61		0.88	0.024		0.035
C	0.46		0.70	0.018		0.028
C2	1.21		1.32	0.048		0.052
C3	2.40		2.72	0.094		0.107
D	8.60		9.70	0.339		0.382
E	9.60		10.4	0.378		0.409
F	6.20		6.60	0.244		0.260
G		2.54			0.1	
H	28.0		29.8	1.102		1.173
L1		3.75			0.148	
L2	1.14		1.70	0.045		0.067
L3	2.65		2.95	0.104		0.116
V1		45°			45°	

### CHARACTERISTIC CURVES

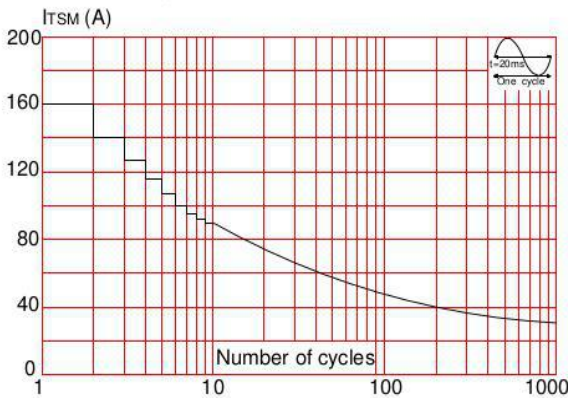
**FIG.1** Maximum power dissipation versus RMS on-state current



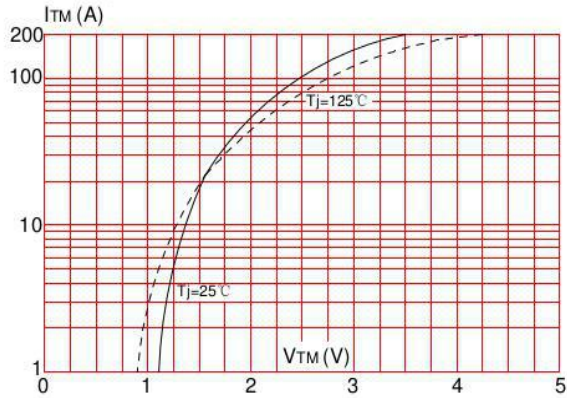
**FIG.2:** RMS on-state current versus case temperature



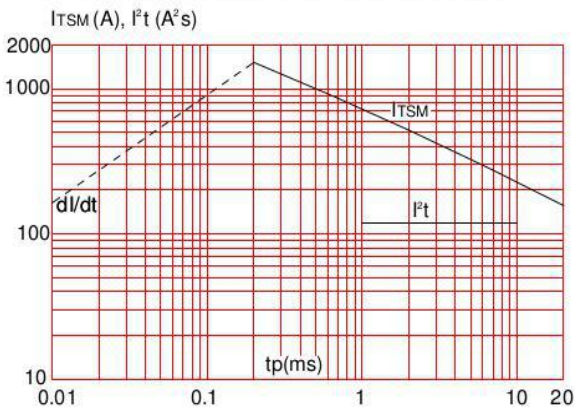
**FIG.3:** Surge peak on-state current versus number of cycles



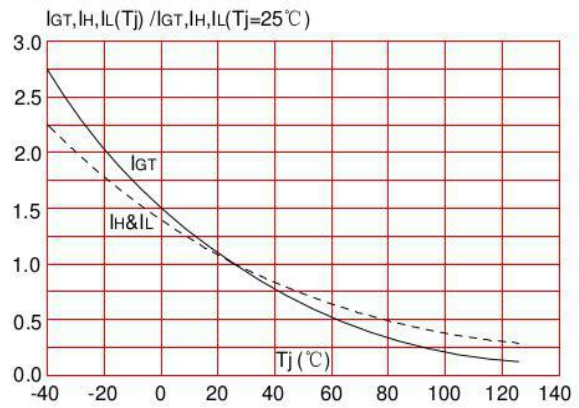
**FIG.4:** On-state characteristics (maximum values)



**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 20\text{ms}$ , and corresponding value of  $I^2t$  ( $di/dt < 50\text{A}/\mu\text{s}$ )



**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature





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## Customer Notes

### Component Disposal Instructions

1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

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